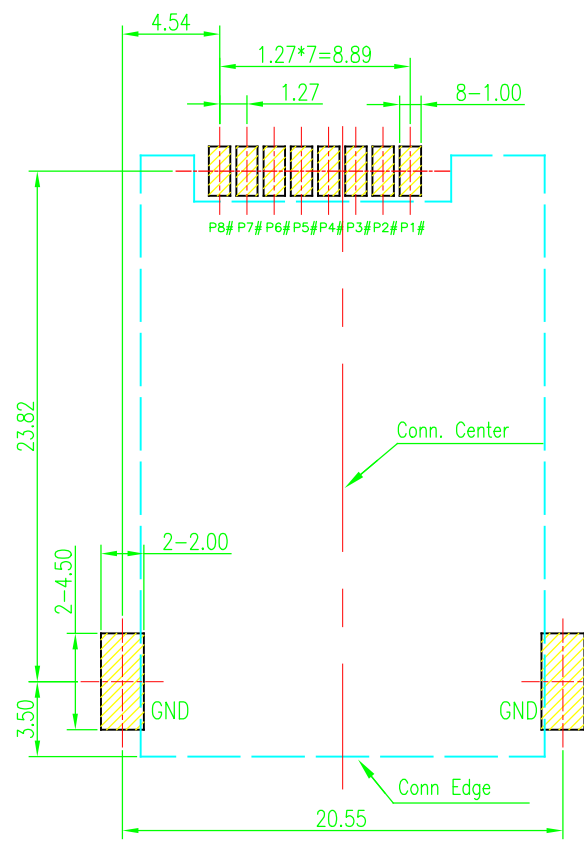
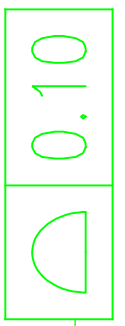
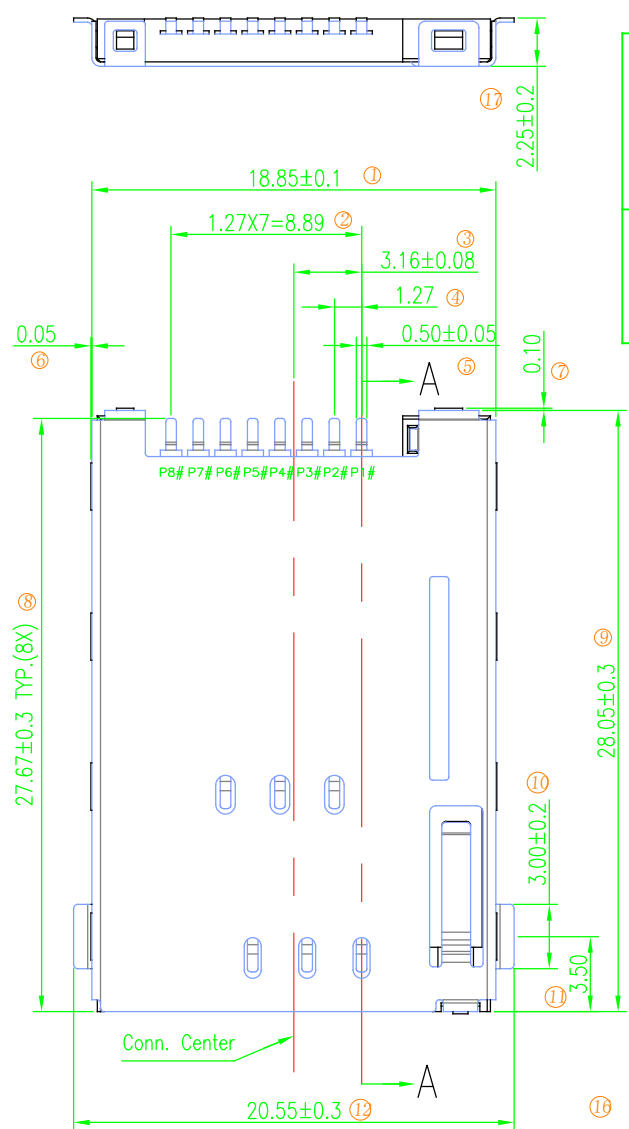
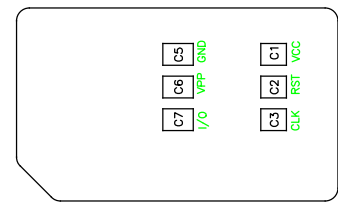


REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	10/09'15	Yang		WEI

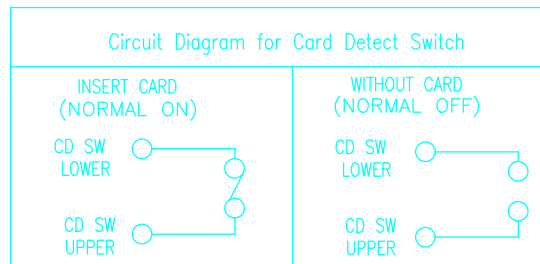
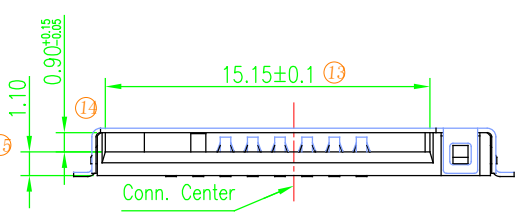


Specification

- * Electrical Characteristics :
 - Current Rating: 0.5A AC/DC Max.
 - Dielectric Withstanding Voltage: 250V AC/DC
 - Insulation Resistance: 500M ohms Min.
 - Contact Resistance: 100m ohms Max.
- * Mechanical Characteristics:
 - Mating Cycles: 5000 Insertions.
- * Environmental :
 - Operating Temperature: -40°C to +85°C.
- * Material:
 - Housing: HI-Temp plastic UL 94V-0 Rated.
 - Contact: Copper Alloy.
 - Shell: Stainless Steel, t=0.20mm.
- * Plating :
 - Terminal:
 - Contact area: G/F Plated Over Nickel.
 - Solder area: Tin Plated Over Nickel.
 - Under plate: Nickel.
 - Shell:
 - Nickel Plated Over All,
 - Solder Area: Gold Flash.



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	CD SW LOWER
P8#	CD SW UPPER



SOLDER AREA

MILLIMETERS	INCH	UNITS			
X.° ± 2'	X.° ± 2'	MM			
.X ± 0.30	.XX ± 0.012	MAT'L			
.XX ± 0.20	.XXX ± 0.008	SEE NOTES	PART NUMBER:		
.XXX ± 0.10	.XXXX ± 0.004	FINISH	TITLE: SIM card 6+2 pin push H2.2		
		SEE NOTES	APPD: WEI		
		QTY	CHKD:		
		SEE NOTES	DR: Yang		
			DWG NO.:		
			SCALE	SHEET	REV.
			1:1	1/2	A0